



# MIC2551

## USB Transceiver

### General Description

The MIC2551 is a single chip transceiver that complies with the physical layer specifications of the Universal Serial Bus (USB) 2.0. It supports both full speed (12Mbps) and low speed (1.5Mbps) operation. It is also designed to operate down to 1.6V in order to be compatible with lower system voltages of most mobile systems.

### Features

- Compliant to USB Specification Revision 2.0 for full speed (12Mbps) and low speed (1.5Mbps) operation
- Compliant to IEC-61000-4.2 (Level 3)
- Separate I/O supply with operation down to 1.6V
- Integrated speed select termination supply
- Very-low power consumption to meet USB suspend-current requirements
- Small TSSOP and MLF<sup>®</sup> packages
- No power supply sequencing requirements
- Software controlled re-enumeration

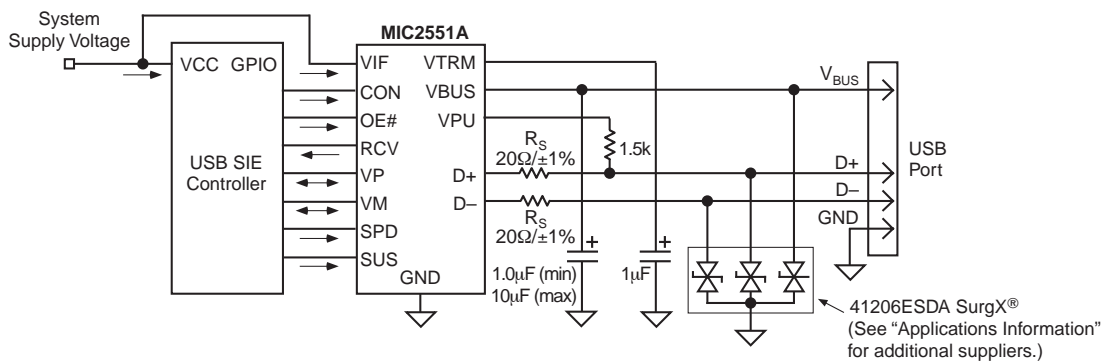
### Applications

- PDAs
- Palmtops
- Cell phones

### Ordering Information

Part Number		Package
Standard	Pb-Free	
MIC2551BTS	MIC2551YTS	14-Pin TSSOP
MIC2551BML	MIC2551YML	16-Pin MLF <sup>®</sup>

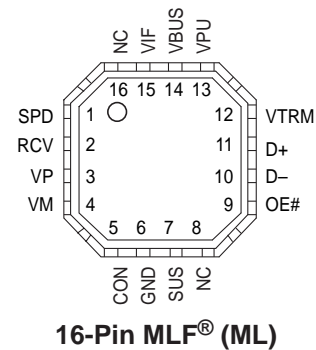
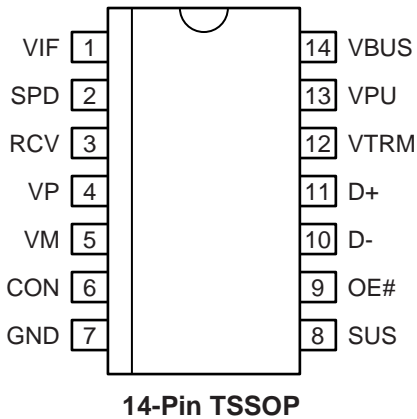
### Typical Application



Typical Application Circuit

MicrLeadFrame and MLF are registered trademarks of Amkor Technology. SurgX is a registered trademark of Cooper Electronics Technologies.

## Pin Configuration



## Pin Description

Pin Number MIC2551BTS	Pin Number MIC2551BML	Pin Name	I/O	Pin Function
1	15	VIF	I	System Interface Supply Voltage: Used to provide reference supply voltage for system I/O interface signaling.
2	1	SPD	I	Edge Rate Control: A logic HIGH operates at edge rates for "full speed" operation. A logic LOW operates edge rates for "low speed" operation.
3	2	RCV*	O	Receive Data: Output for USB differential data.
4	3	VP*	I/O	If OE# = 1, VP = Receiver output (+) If OE# = 0, VP = Driver input (+)
5	4	VM*	I/O	If OE# = 1 VM, = Receiver output (-) If OE# = 0, VM = Driver input (-)
6	5	CON	I	CONNECT (Input): Controls state of VPU. Refer to VPU pin description for detail.
7	6	GND		Ground Reference.
8	7	SUS	I	Suspend: Active-High. Turns off internal circuits to reduce supply current.
9	9	OE#*	I	Output Enable: Active-Low. Enables the transceiver to transmit data onto the bus. When not active, the transceiver is in the receive mode.
10/11	10/11	D-, D+*	I/O	Differential data lines conforming to the USB standard.
12	12	VTRM	O	3.3V Reference Supply Output: Requires a minimum 0.1 $\mu$ F decoupling capacitor for stability, 1 $\mu$ F recommended. <sup>4</sup>
13	13	VPU	O	Pull-up Supply Voltage Output: Used to connect 1.5k $\Omega$ pull-up speed detect resistor. If CON = 1, VPU is high impedance. If CON = 0, VPU = 3.3V.
14	14	VBUS	I	USB Bus Supply Voltage: Used to power USB transceiver and internal circuitry.
	8,16	NC		No connect.

\* See Table 1 for description of logic states.

SUS	OE#	D+, D-	RCV	VP/VM	Function
0	0	Driving	Active	Active	Normal transmit mode
0	1	Receiving	Active	Active	Normal receive mode
1	0	Hi-Z	0	Not active	Low power state
1	1	Hi-Z	0	Active	Receiving during suspend (low power state) (Note 1)

Note 1. During suspend VP and VM are active in order to detect out of band signaling conditions.

**Table 1. Function Selection**

OE# = 0:					
Input		Output			Result
VP	VM	D+	D-	RCV	
0	0	0	0	X	SE0
0	1	0	1	0	Logic 0
1	0	1	0	1	Logic 1
1	1	1	1	X	Undefined
OE# = 1:					
Input		Output			Result
D+	D-	VP	VM	RCV	
0	0	0	0	X	SE0
0	1	0	1	0	Logic 0
1	0	1	0	1	Logic 1
1	1	1	1	X	Undefined

X - Undefined

**Table 2. Truth Table During Normal Mode**

**Absolute Maximum Ratings (Note 1)**

Supply Voltage ( $V_{BUS}$ )	6.5V
All Other Inputs	-0.5V to 5.5V
Ambient Storage Temperature	-65°C to +150°C
Output Current (D+, D-)	± 50mA
Output Current (all others)	±15mA
Input Current	±50mA

**ESD, Note 3**

$V_{BUS}$ , D+, D-	±11KV
All other pins	±2KV

**Operating Ratings (Note 2)**

Ambient Operating Temperature	-40°C to +85°C
Package Thermal Resistance	
TSSOP ( $\theta_{JA}$ )	100°C/W
MLF® ( $\theta_{JA}$ )	59°C/W

**DC Electrical Characteristics (System and USB Interface) (Note 7)**

$V_{IF} = 3.6V$ ,  $V_{BUS} = 5V$  unless otherwise noted;  $T_A = 25^\circ C$ . **Bold** indicates specifications over temperature, -40°C to 85°C.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$V_{BUS}$	USB Supply Voltage		<b>4.0</b>		<b>5.25</b>	V
$V_{IF}$	System I/F Supply Voltage		<b>1.6</b>		<b>3.6</b>	V
$V_{IL}$	LOW-Level Input Voltage, <b>Note 4</b>		$V_{IF}-0.3$		$0.15V_{IF}$	V
$V_{IH}$	HIGH-Level Input Voltage, <b>Note 4</b>		$0.85V_{IF}$		$V_{IF}+0.3$	V
$V_{OH}$	HIGH-Level Output Voltage, <b>Note 4</b>	$I_{OH} = 20\mu A$	$0.9V_{IF}$			V
$V_{OL}$	LOW-Level Output Voltage, <b>Note 4</b>	$I_{OL} = 20\mu A$			0.1	V
$I_{IL}$	Input Leakage Current, <b>Note 4</b>		<b>-5</b>		<b>5</b>	$\mu A$

Symbol	Parameter	Conditions					Min	Typ	Max	Units
		SPD	SUS	OE#	Voltage	Load				
$I_{IF}$	VIF Supply Current	1	0	1	$V_{BUS} = 5.25V$ $V_{IF} = 3.6V$		1	<b>5</b>	$\mu A$	
		1	0	0			1	<b>5</b>	$\mu A$	
		0	0	1			1	<b>5</b>	$\mu A$	
		0	0	0			1	<b>5</b>	$\mu A$	
		0	1	0			1	<b>5</b>	$\mu A$	
		1	0	0		$f = 6MHz$ CLOAD $= 50 pF$ , <b>Note 7</b>	325	<b>650</b>	$\mu A$	
		0	0	0		$f = 750kHz$ CLOAD = 600 pF <b>Note 7</b>	40	<b>75</b>	$\mu A$	
$I_{VBUS}$	VBUS Supply Current	1	0	1	$V_{BUS} = 5.25V$ $V_{IF} = 3.6V$		800	1100	$\mu A$	
		1	0	0			3000	<b>5000</b>	$\mu A$	
		0	0	1			230	<b>350</b>	$\mu A$	
		0	0	0			400	700	$\mu A$	
		0	1	0			130	200	$\mu A$	
		1	0	0		$f = 6MHz$ CLOAD $= 50 pF$ , <b>Note 7</b>	7.3	<b>10</b>	mA	
		0	0	0		$f = 750kHz$ CLOAD = 600 pF <b>Note 7</b>	3.6	<b>5</b>	mA	
$I_{VPULEAK}$	VPU Leakage Current	CON = 1, $V_{PU} = 0V$					<b>-5</b>		<b>5</b>	$\mu A$
$I_{VIFLEAK}$	VIF Leakage Current	$V_{IF} = 3.6V$ , $V_{BUS} = 0V$					<b>-5</b>		<b>5</b>	$\mu A$
$V_{PU}$	Pull-Up Output Voltage	$I_{TERM} = 200\mu A$ , $V_{BUS} = 4.0$ to $5.25V$					<b>3.0</b>	3.3	<b>3.6</b>	V
$R_{SW}$	Internal Pull-Up Termination	$I_{TERM} = 10mA$ , $V_{BUS} = 4.0$ to $5.25V$						10		$\Omega$

**ESD Protection**

IEC-1000-4-2	Air Discharge	10 pulses		±8		kV
(D+, D-, $V_{BUS}$ only)	Contact Discharge	10 pulses		±9		kV

**DC Electrical Characteristics (Transceiver) (Note 7)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Leakage Current</b>						
$I_{LO}$	Hi-Z State Data Line Leakage (Suspend Mode)	$0V < V_{IN} < 3.3V$ , SUS = 1	-10		10	$\mu A$
<b>Input Levels</b>						
$V_{DI}$	Differential Input Sensitivity	$ (D+) - (D-) $	0.2			V
$V_{CM}$	Differential Common Mode Range	Includes $V_{DI}$ range	0.8		2.5	V
$V_{SE}$	Single Ended Receiver Threshold		0.8		2.0	V
	Receiver Hysteresis			200		mV
<b>Output Levels</b>						
$V_{OL}$	Static Output Low	$R_L = 1.5k\Omega$ to 3.6V			0.3	V
$V_{OH}$	Static Output High	$R_L = 15k\Omega$ to GND	2.8		3.6	V
<b>Capacitance</b>						
$C_{IN}$	Transceiver Capacitance	Pin to GND		10		pF
$Z_{DRV}$	Driver Output Resistance	Steady state drive	8	16	24	$\Omega$

**AC Electrical Characteristics (Notes 6, 7)****Driver Characteristics (Low Speed)**

$T_R$	Transition Rise Time	$C_L = 50pF$ , Figure 2 $C_L = 600pF$	75		300	ns
$T_F$	Transition Fall Time	$C_L = 50pF$ , Figure 2 $C_L = 600pF$	75		300	ns
$T_R, T_F$	Rise/Fall Time Matching	$(T_R, T_F)$	80		125	%
$V_{CRS}$	Output Signal Crossover Voltage		1.3		2.0	V

**Driver Characteristics (Full Speed)**

$T_R$	Transition Rise Time	$C_L = 50pF$ , Figure 2	4		20	ns
$T_F$	Transition Fall Time	$C_L = 50pF$ , Figure 2	4		20	ns
$T_R, T_F$	Rise/Fall Time Matching	$(T_R, T_F)$	90		111.11	%
$V_{CRS}$	Output Signal Crossover Voltage		1.3		2.0	V

**Transceiver Timing**

$t_{PVZ}$	OE# to RCVR Tri-State Delay	Figure 1			15	ns
$t_{PZD}$	Receiver Tri-State to Transmit Delay	Figure 1	15			ns
$t_{PDZ}$	OE# to DRVR Tri-State Delay	Figure 1			15	ns
$t_{PZV}$	Driver Tri-State to Receive Delay	Figure 1	15			ns
$t_{PLH}$ $t_{PHL}$	VP, VM to D+, D- Propagation Delay	Figure 4			15	ns
$t_{PLH}$ $t_{PHL}$	D+, D- to RCV Propagation Delay	Figure 3			15	ns
$t_{PLH}$ $t_{PHL}$	D+, D- to $V_P, V_M$ Propagation Delay	Figure 3			8	ns

**Note 1.** Exceeding the absolute maximum rating may damage the device.

**Note 2.** The device is not guaranteed to function outside its operating rating.

**Note 3.** Devices are ESD sensitive. Handling precautions recommended. Human body model, 1.5k in series with 100pF.

**Note 4.** Specification applies to the following pins: SUS, SPD, RCV, CON, RCV, VP, VM, OE#.

**Note 5.** Characterized specification(s), but not production tested.

**Note 6.** All AC parameters guaranteed by design but not production tested.

**Note 7.** Specification for packaged product only.

## Timing Diagrams

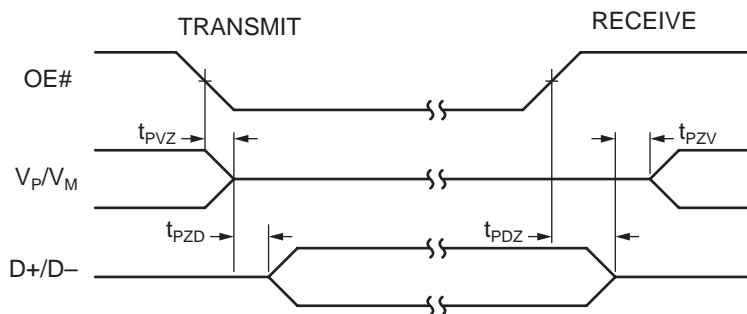


Figure 1. Enable and Disable Times

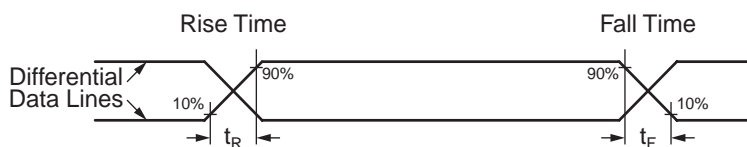


Figure 2. Rise and Fall Times

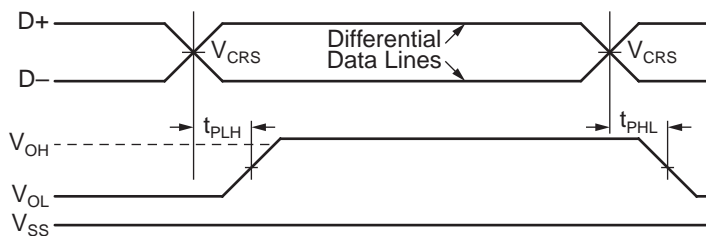


Figure 3. Receiver Propagation Delay

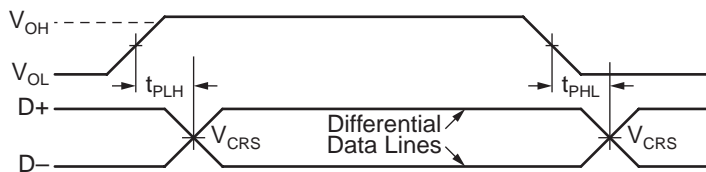


Figure 4. Driver Propagation Delay

## Test Circuits

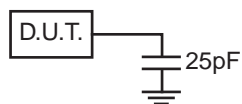


Figure 5. Load for  $V_P$ ,  $V_M$ , RCV

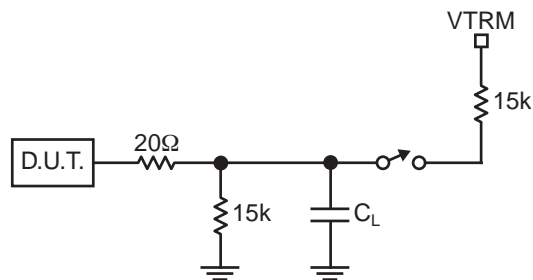
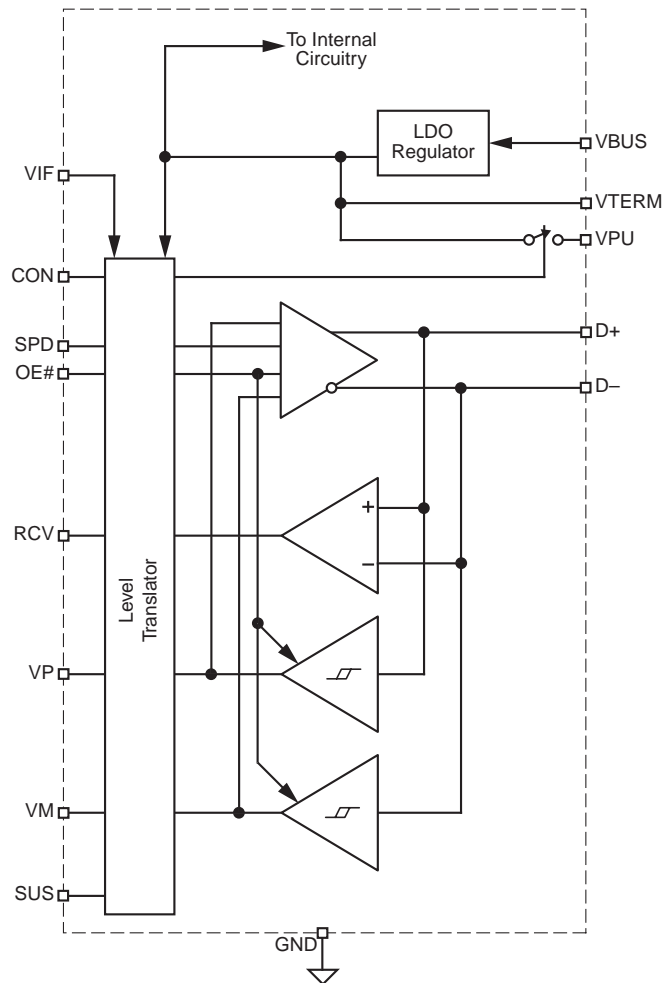


Figure 6. Load for  $D_+$ ,  $D_-$

## Functional Diagram



MIC2551 Block Diagram

## Functional Description

The MIC2551 is designed to provide USB connectivity in mobile systems where available system supply voltages are not able to satisfy USB requirements. The MIC2551 can operate down to supply voltages of 1.6V and still meet USB physical layer specifications. As shown in the circuit above, the MIC2551 takes advantage of the USB supply voltage,  $V_{BUS}$ , to operate the transceiver. The system voltage,  $V_{IF}$ , is used to set the reference voltage used by the digital I/O lines interfacing to the system controller. Internal circuitry provides translation between the USB and system voltage domains.  $V_{IF}$  will typically be the main supply voltage rail for the controller.

In addition, a 3.3V, 10% termination supply voltage,  $V_{PU}$ , is provided to support speed selection.  $V_{PU}$  can be disabled or enabled under software control via the CON input. This allows for software-controlled connect or disconnect states. A 1.5k resistor is required to be connected between this pin and the D+ or D- lines to respectively specify high speed or low speed operation.

The use of ESD transient protection devices is not required for operation, but is recommended. The MIC2551 is ESD rated for 11kV at the VBUS and D+, D- pins and 2kV for all other pins.

## Application Information

### Power Supply Configuration

The MIC2551 can be set up for different power supply configurations which modify the behavior of the device. Both  $V_{BUS}$  and  $V_{IF}$  have special thresholds that detect when they are either removed or grounded. Table 3 depicts the behavior under the different power supply configuration scenarios that are explained below.

#### Normal Mode

$V_{BUS}$  is connected to the 5.0V USB bus voltage and  $V_{IF}$  is connected to a supply voltage in the range of 1.6V to 3.6V. In this case  $V_{TRM}$  supplies a 3.3V voltage for powering the speed select resistor via  $V_{PU}$  depending on the state of the CON pin.

#### Disconnect Mode

$V_{IF}$  is connected to a supply in a range of 1.6V to 3.6V and  $V_{BUS}$  is open or grounded. If  $V_{BUS}$  is opened while transmitting, the data lines (D+, D-) have sharing capability and may be driven with external devices up to approximately 3.6V if, and only if, SUSPEND is enabled ( $SUS = 1$ ). With  $V_{BUS}$  ground, D+, D- sharing mode is not permitted.

#### Disable Mode

$V_{BUS}$  is connected to the 5.0V USB bus voltage and  $V_{IF}$  is open. All logic controlled inputs become high impedances, thus minimal current will be supplied by  $V_{IF}$  if the input pins are pulled up to an external source.

### Alternate Power Supply Configuration Options

#### I/O Interface Using 3.3V

In systems where the I/O interface utilizes a 3.3V USB controller, an alternate solution is shown in Figure 7. No extra components are required; however, the load on  $V_{TRM}$  must not exceed 10mA.

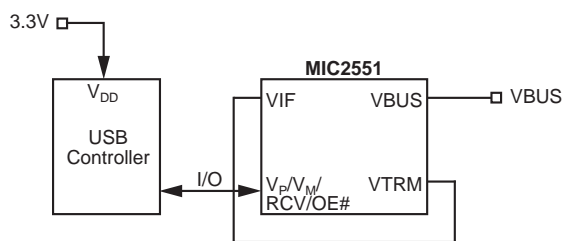


Figure 7. I/O Interface Uses 3.3V

### Signal Amplitude Respective to $V_{IF}$

When operating the MIC2551, it is necessary to provide input signals which do not exceed  $V_{IF} + 0.3V$ .

### External ESD Protection

The use of ESD transient protection devices is not required for operation, but is recommended. We recommend the following devices or the equivalent:

Cooper Electronic Technologies ([www.cooperet.com](http://www.cooperet.com))

41206ESDA SurgX<sup>®</sup>

0805ESDA SurgX<sup>®</sup>

Littelfuse ([www.littelfuse.com](http://www.littelfuse.com))

V0402MHS05

SP0503BAHT

### Non-Multiplexed Bus

In order to save pin count for the USB logic controller interface, the MIC2551 was designed with  $V_P$  and  $V_M$  as bi-directional pins. To interface the MIC2551 with a non-multiplexed data bus, resistors can be used for low cost isolation as shown in Figure 8.

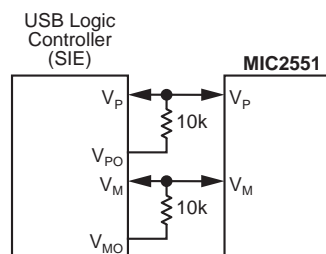


Figure 8. MIC2551 Interface to Non-Multiplexed Data Bus

Configuration Mode	VBUS/VTRM	VIF	Notes
Normal	Connected	Connected	Normal supply configuration and operation.
Disconnect (D+/D- sharing)	Open	Connected	VP/VM are HIGH outputs, RCV is LOW. With OE# = 0 and SUS = 1, data lines may be driven with external devices up to 3.6V. With D+, D- floating, I <sub>IF</sub> draws less than 1μA.
Disconnect	Ground	Connected	VP/VM are HIGH outputs, RCV is LOW. With D+, D- floating, I <sub>IF</sub> draws less than 1μA.
Disable Mode	Connected	Open	Logic controlled inputs pins are Hi-Z.
Prohibited	Connected	Ground	Prohibited condition.

Table 3. Power Supply Configuration

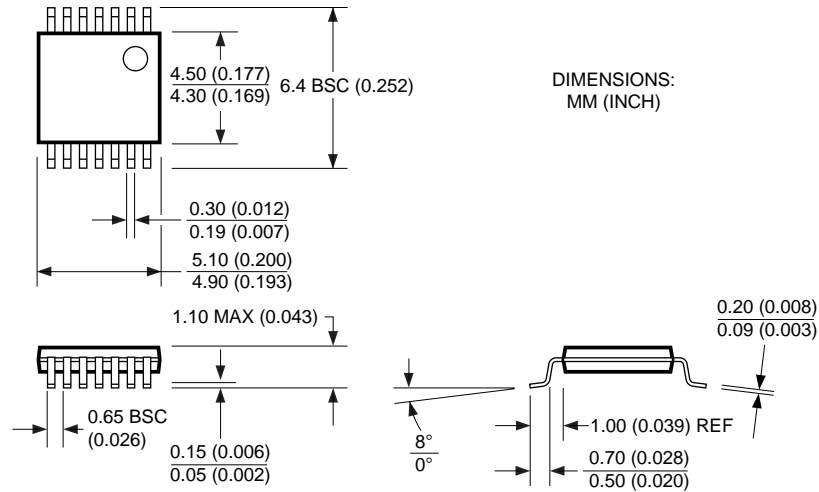


## PCB Layout Recommendations

Although the USB standard and applications are not based in an impedance controlled environment, a properly designed PCB layout is recommended for optimal transceiver performance. The suggested PCB layout hints are as follows:

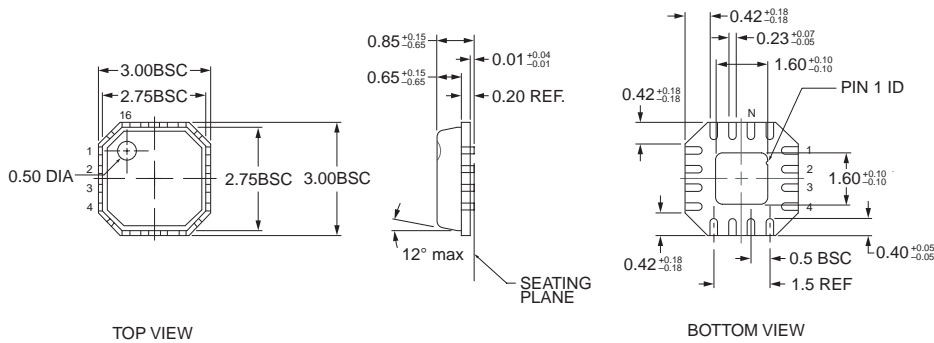
- Match signal line traces (VP/VM, D+, D-) to 40ps, approximately  $\frac{1}{3}$  inch if possible. FR-4 PCB material propagation is about 150ps/inch, so to minimize skew try to keep VP/VM, D+/D- traces as short as possible.
- For every signal line trace width (w), separate the signal lines by 1.5–2 widths. Place all other traces at >2 widths from all signal line traces.
- Maintain the same number of vias on each differential trace, keeping traces approximately at same separation distance along the line.
- Control signal line impedances to  $\pm 10\%$ .
- Keep  $R_S$  as close to the IC as possible, with equal distance between  $R_S$  and the IC for both D+ and D-.

Package Information



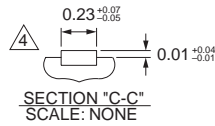
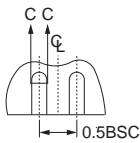
DIMENSIONS:  
MM (INCH)

14-lead TSSOP (TS)



TOP VIEW

BOTTOM VIEW

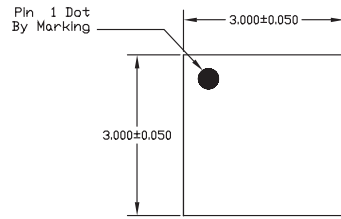


1. DIMENSIONS ARE IN mm.
2. DIE THICKNESS ALLOWABLE IS 0.305mm MAX.
3. PACKAGE WARPAGE MAX 0.05mm.
4. THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20mm AND 0.25mm FROM TIP.
5. APPLIES ONLY FOR TERMINALS

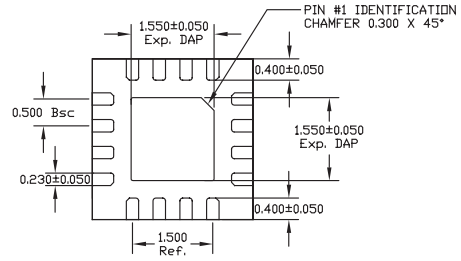
FOR EVEN TERMINAL/SIDE

Rev. 02

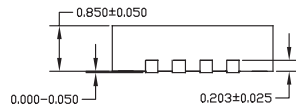
16-Pin MLF® (ML)



TOP VIEW



BOTTOM VIEW



SIDE VIEW

- NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
  2. MAX. PACKAGE WARPAGE IS 0.05 mm.
  3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
  4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.

16-Pin MLF® (ML)

MICREL INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB <http://www.micrel.com>

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